The United States América

The Director of the United States Patent and Trademark Office

Has received an application for a patent for a new and useful invention. The title and description of the invention are enclosed. The requirements of law have been complied with, and it has been determined that a patent on the invention shall be granted under the law.

Therefore, this

United States Patent

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Jon W. Dudas



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(54) DISCRETE CIRCUIT COMPONENT HAVING AN UP-RIGHT CIRCUIT DIE WITH LATERAL ELECTRICAL CONNECTIONS

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- (*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 0 days.
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(57) ABSTRACT

A discrete circuit component having an up-right circuit die with lateral electrical connections. The component comprises a substrate having a pair of electrically conductive traces, and a circuit die is planted between the pair of consecutive traces, wherein one electrode of the circuit die on the surface thereof vertical to the substrate is electrically bonded to one of the conductive trace immediately next thereto, while the other electrode of the circuit die on the opposite surface thereof vertical to the substrate is electrically bonded to the other of the pair of conductive traces immediately next thereto. A body of electrical insulation material hermetically seals the circuit die, and a pair of surface electrodes formed on the surface of the body of insulation material are each electrically connected to the corresponding one of the pair of electrically conductive traces extending from the circuit die.

17 Claims, 5 Drawing Sheets



